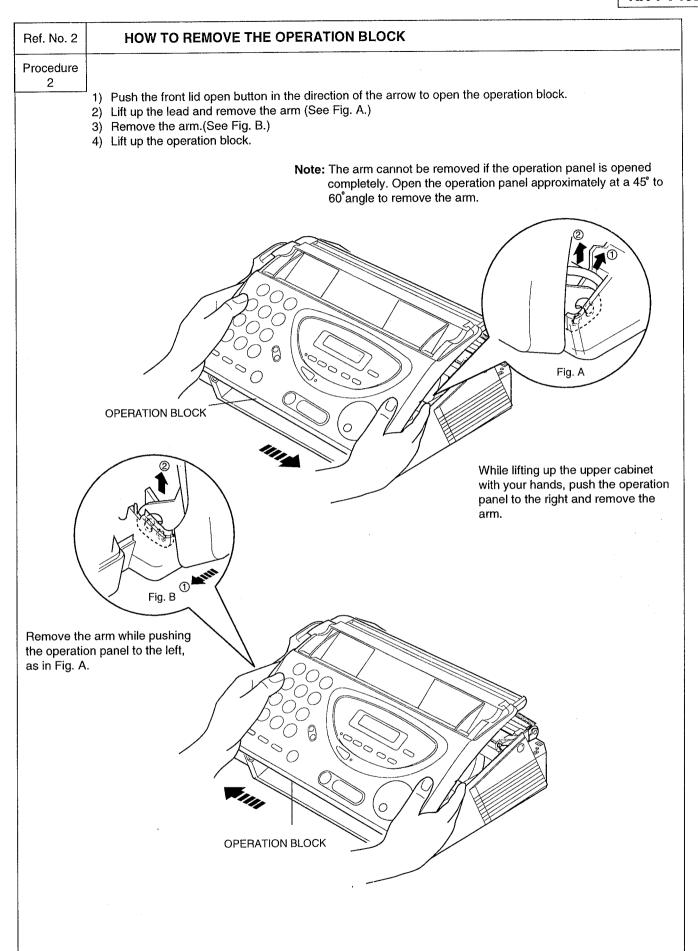
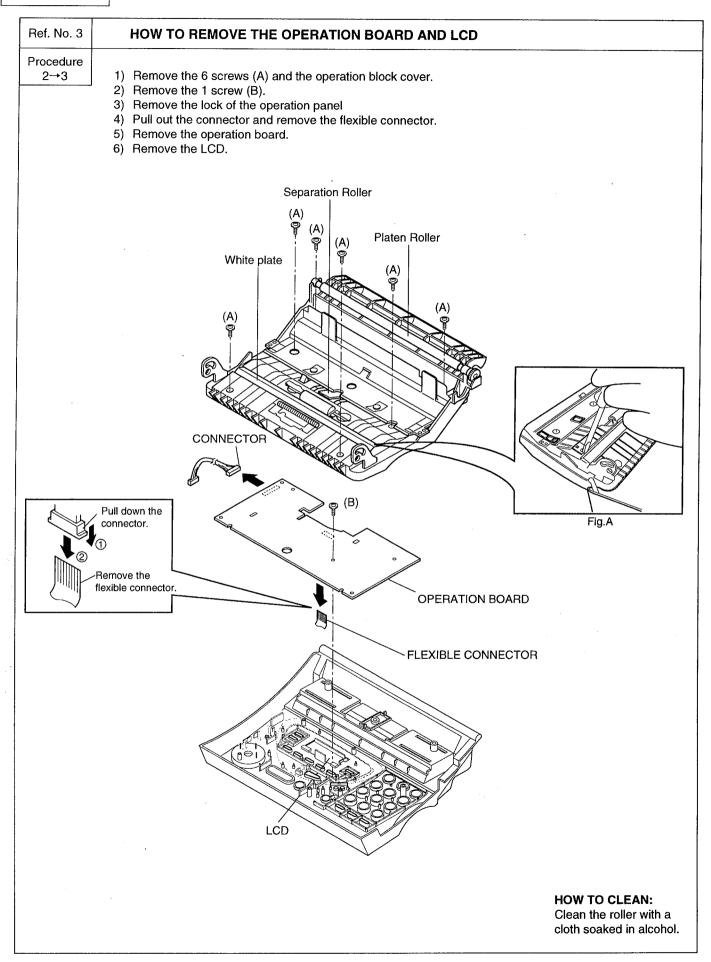
DISASSEMBLY INSTRUCTIONS

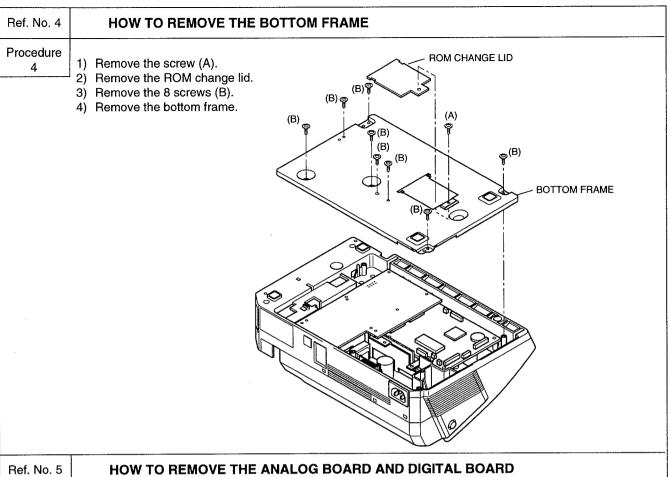
Pa	ιge
How to Remove the Handset Cradle Cabinet	94
How to Remove the Operation Block	95
How to Remove the Operation Board and LCD	96
How to Remove the Bottom Frame	97
How to Remove the Analog and Digital Board	97
How to Remove the Power Supply Board, Speaker and AC Inlet 9	98
How to Remove the Cutter and Motor Block	99
How to Remove the Image Sensor	00
How to Remove the Rollers10	00
How to Remove the Thermal Head Roller10	01
How to Remove the Document Tray 10	02
How to Replace the Flat Package IC	04

Ref. No. 1 HOW TO REMOVE THE HANDSET CRADLE CABINET Procedure 1) Push the front lid open button to open the operation block. 2) Remove the 2 screws (A). 3) Remove the handset cradle cabinet. (See Fig. A.) Caution: If you try to remove the handset cradle in the opposite direction, the rib will break. Fig. A RIB FRONT LID OPEN BUTTON ● HOW TO ATTACH THE HANDSET CRADLE CABINET 1) Insert the handset cabinet into the side of the unit.(See Fig.B.) 2) Be careful not to bend the cabinet.

Fig. B



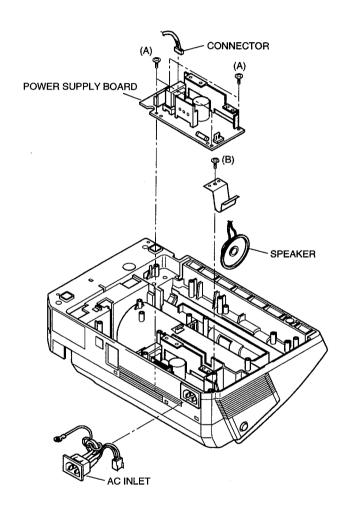


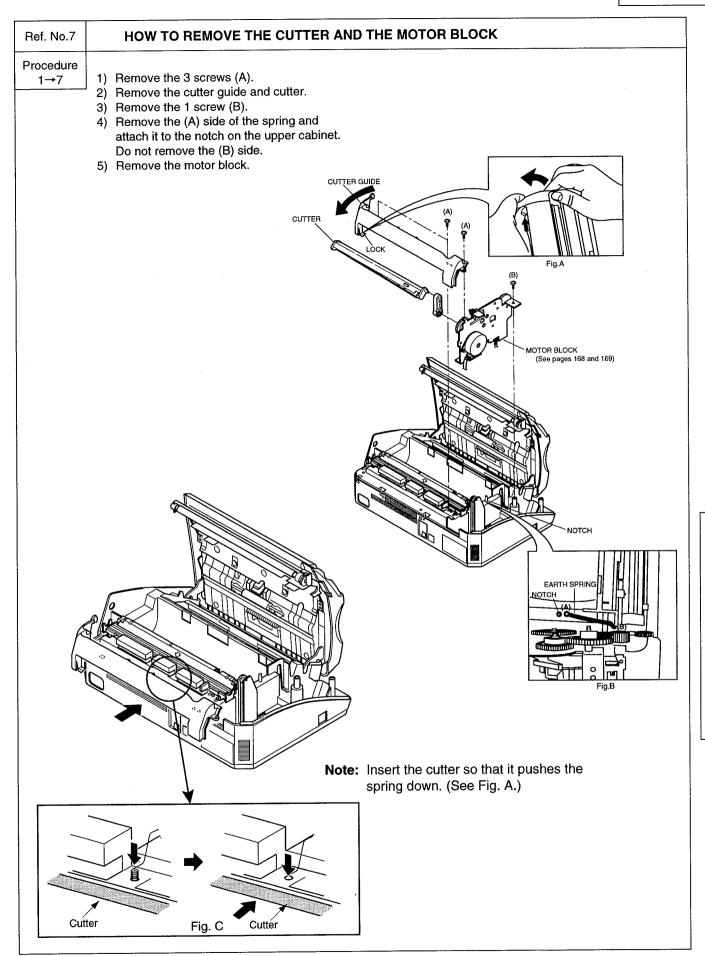


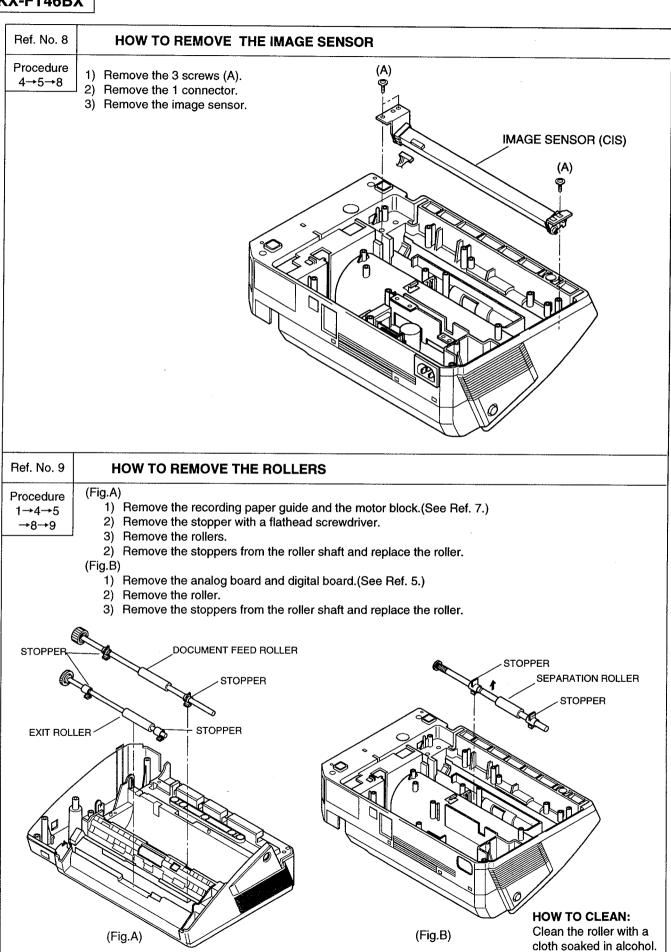
Procedure 4→5 1) Remove the 3 screws (A). 2) Remove the 1 connector. 3) Remove the 7 connectors. 5) Remove the 2 screws (A). 6) Remove the digital board. (A) CONNECTORS CONNECTORS CONNECTORS CONNECTORS

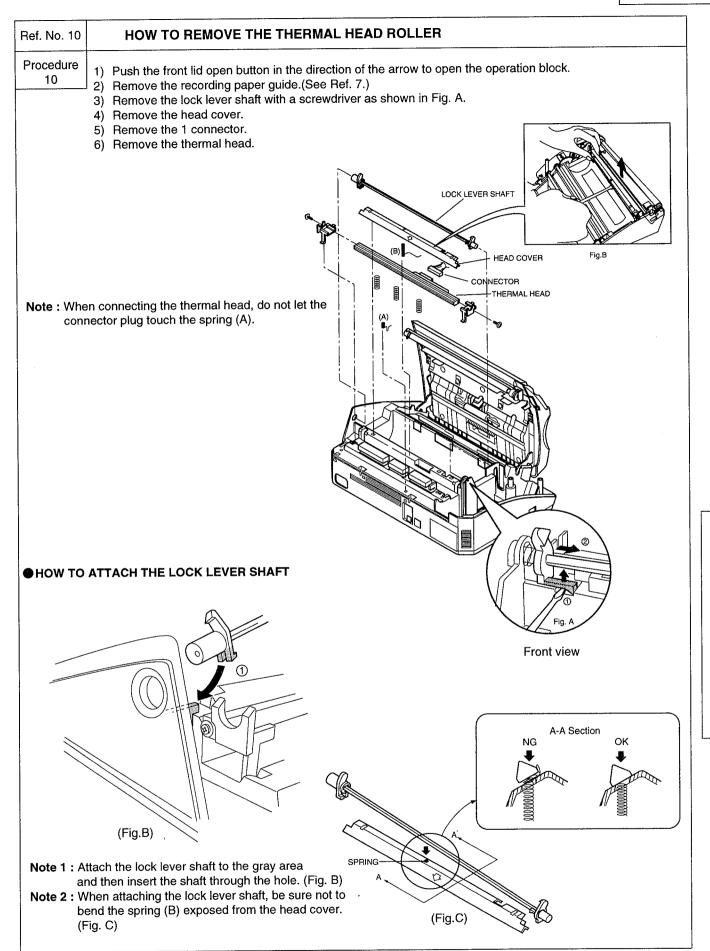
Ref. No. 6	HOW TO REMOVE THE POWER SUPPLY BOARD, SPEAKER AND AC INLET
Procedure 4→5→6	

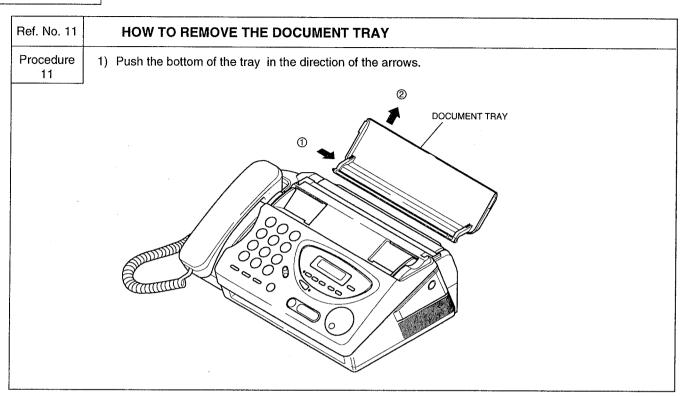
- Remove the 4 screws (A) and remove the power supply board.
 Remove the 1 screw (B).
 Remove the AC inlet.



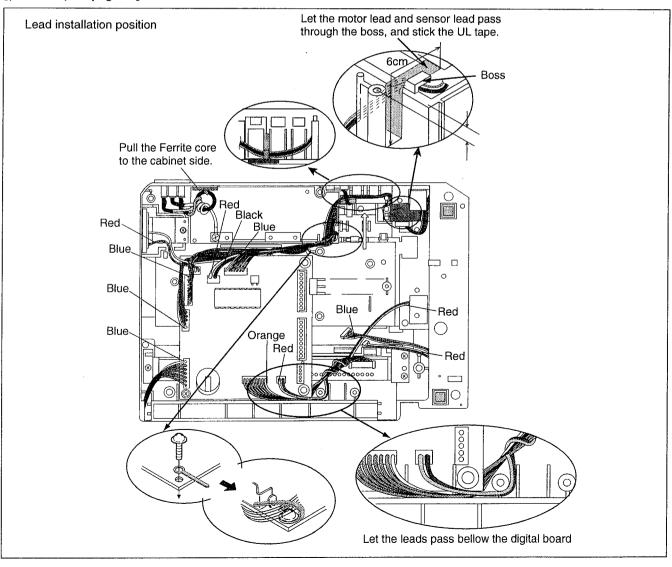








[(Ref. No.5) for page 97]



HOW TO REPLACE THE FLAT PACKAGE IC

If you do not have the special tools (for example: SPOT HEATER) to remove the SPOT HEATER'S Flat IC, if you have solder (large amount), a soldering iron, and a cutter knife, you can easily remove the ICs even if there are more than 100 pins.

1. PREPARATION

SOLDER - - - - - - Sparkle Solder 115A-1, 115B-1
OR
Almit Solder KR-19, KR-19RMA

Soldering iron - - - - Recommended power consumption is between 30 W to 40 W.
Temperature of Copper Rod 662 ± 50 °F (350 ±10 °C)

(An expert may handle a 60~80 W iron, but a beginner might damage the foil by overheating.)

Flux - - - - - - HI115 Specific gravity 0.863

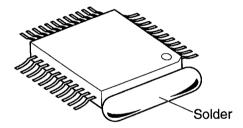
(Original flux should be replaced daily.)

2. FLAT PACKAGE IC REMOVAL PROCEDURE

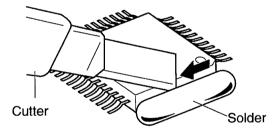
1. Put plenty of solder on the IC pins so that the pins can be completely covered.

Note:

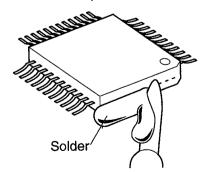
If the IC pins are not soldered enough, you may give pressure to the P.C. board when cutting the pins with a cutter.



2. Make a few cuts into the joint (between the IC and its pins) first and then cut off the pins thoroughly.



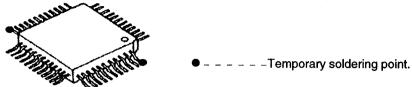
3. While the solder melts, remove it together with the IC pins.



When you attach a new IC to the board, remove all solder left on the land with some tools like a soldering wire. If some solder is left at the joint on the board, the new IC will not be attached properly.

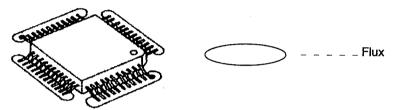
3. FLAT PACKAGE IC INSTALLATION PROCEDURE

1) Temporarily fix the FLAT PACKAGE IC by soldering on the two marked pins.

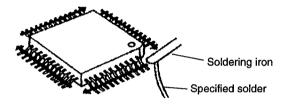


*Check the accuracy of the IC setting with the corresponding soldering foil.

2) Apply flux to all pins of the FLAT PACKAGE IC.



3) Solder the pins, sliding the soldering iron in the direction of the arrow.



4. BRIDGE MODIFICATION PROCEDURE

- 1) Lightly re-solder the bridged portion.
- 2) Remove the remaining solder along the pins using a soldering iron as shown in the figure below.

